

Application No. 10/606,525
SD-7139.1

REMARKS

Claim Status

Claims 1-47 are pending.

Claims 1-5, 13, 14, 17-20 and 22-47 were withdrawn from consideration.

Claims 6-12, 15, 16 and 21 are rejected.

Claim Amendments

Claims 1-5, 21, and 23-47 are cancelled.

Claims 13, 14, 17-20 and 22 are withdrawn.

New claim 48 was added.

Claim 6 was amended to replace the word "made" with --formed--. Also, the phrase "; but not" was replaced with --, but not --. The following text was added to claim 6:

wherein the thickness of the protective coating is less than or equal to 100 microns.

Claim 8 was amended to replace "Ceramic DIP, CERDIP" with --ceramic dual inline packaging (or, CERDIP) --.

Claims 9-11 were amended to delete the word "further".

Claim 11 was amended to include the following text:

wherein the device of claim 11 is an intermediate structure that represents an intermediate stage in a process for fabricating a working MEMS device; and wherein said intermediate structure can be made functional by releasing the MEMS elements, while not removing the protective coating from the first and second electrical conductors, the electrical interconnection, and the passive area.

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Claim Objections

Claims 6, 8, and 9-11 were objected to because of minor informalities. Applicants have made the amendments suggested by the Examiner.

Claim 15 was objected to for reciting subject matter that is not fully supported in the specification. In response, Applicants have amended the Specification to include a specific reference to a **chemical vapor deposited coating** in order to conform the specification to the claims. No new matter has been added, because the claims-as-filed disclosed a **chemical vapor deposited coating**.

Claim 21 was cancelled.

Claim Rejections – 35 USC 112

Claim 11 was rejected under 35 USC 112, first paragraph, as failing to comply with the written description requirement. In response, applicants amended claim 11 to include the following text:

wherein the device of claim 11 is an intermediate structure that represents an intermediate stage in a process for fabricating a working MEMS device; and wherein said intermediate structure can be made functional by releasing the MEMS elements, while not removing the protective coating from the first and second electrical conductors, the electrical interconnection, and the passive area.

In view of the interview with Examiner Hu, applicants believe that this amendment is sufficient to overcome the rejection of claim 11.

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Claim Rejections – 35 USC 102(e)

Claims 6-12, 15 and 21 were rejected under 35 USC 102(e) as being anticipated by Glenn (US 6,455,927).

In response, applicants have amended independent claim 6 to limit the thickness of the protective coating to being less than or equal to 100 microns. Glenn does not teach or suggest such a thin coating. Instead, Glenn teaches a standard plastic molded bulk encapsulant produced by injection molding or transfer molding. Glenn's plastic molded package is commonly known as a "bulk" encapsulant (which may or may not wrap around the backside of the die), because it has a much greater thickness, e.g., 1000-3000 microns, than a thin vapor-deposited coating (such as parylene), which is less than 100 microns. Also, in Glenn's invention, during injection molding the plastic encapsulant flows and fills-in the open space/volume in-between adjacent wirebonds, leaving no voids or open volume between wirebonds. This is not the case when a thin, conformal coating less than 100 microns is used, as recited in claim 6; it is too thin to bridge across freestanding wirebonds or ball/bump interconnects.

Since Glenn fails to teach all of the limitations of claim 6 as currently amended, the rejection under 102(e) has been overcome, and claim 6 is now in condition for allowance.

Claims 7-12, 15 and 21 depend from allowable claim 6. Accordingly, dependent claims 7-12, 15 and 21 are also allowable.

Claim Rejections – 35 USC 103(a)

Claim 16 was rejected under 35 USC 102(e) as being anticipated by Glenn (US 6,455,927), in view of applicant's admitted prior art.

Claim 16 depends from claim 6. Since claim 6 as amended is allowable, it follows that dependent claim 16 is also allowable.

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New Claim 48

New claim 48, which depends from claim 6, further limits the thickness of the protective coating to be less than or equal to **100 angstroms**. No new matter has been added, and the specification supports the claim (See Specification p. 13, line 27). Glenn clearly does not anticipate such a very thin coating/film.

Withdrawn claims 13, 14, 17-20 and 22

If amended claim 6 is allowed, then applicants respectfully request that claims 13, 14, 17-20 and 22, which all depend from claim 6, be **rejoined** and allowed, since they depend from on an allowed claim.

Error in claim 14

If claim 14 is rejoined and allowed, then applicants wish to correct a typographic error, as follows:

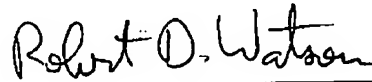
14. (Amended) The microelectronic device of claim [[6]] – 13 –, wherein the package comprises a transparent window disposed across the aperture.

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Applicants have responded to each and every objection and rejection, and urge that claims **6-12, 15, 16 and 48** as presented and amended are now in condition for allowance. Applicants request expeditious processing to issuance.

The Office is authorized to charge **Deposit Account # 19-0131** for any necessary fees regarding this response, including one extra dependent claim (\$ 50), and a 1-month extension of time (\$ 120).

Respectfully submitted,



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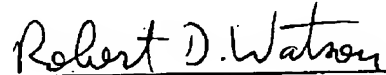
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